RECEIVED
CENTRAL FAX CENTER
MAY 11 2007

IN THE CLAIMS:

1. (Original) A substrate comprising

a metal plate, and

an insulating film, which is provided on the surface of the metal plate and which includes needle alumina particles and granular particles.

2. (Original) The substrate of claim 1, wherein the granular particles include at least one of silica particles, MgO particles, and TiO_2 particles.

3. (Original) The substrate of claim 2, wherein the granular particles include silica particles.

4. (Previously Presented) The substrate of claim 1, wherein the needle alumina particles have an aspect ratio of 6 to 15.

5. (Original) The substrate of claim 4, wherein the needle alumina particles have a major-axis length of 70 nm to 300 nm.

6. (Previously Presented) The substrate of claim 1, wherein the granular particles have a mean particle size of 5 nm to 80 nm.

7. (Previously Presented) The substrate of claim 1, wherein the insulating film includes 0.3 mass% to 80 mass% of the needle alumina particles.

8. (Previously Presented) The substrate of claim 1, wherein the insulating film has a thickness of 0.3 μm to 3.5 μm.

9. (Previously Presented) The substrate of claim 1, wherein the insulating film has a surface roughness of 0.3 μm or less.

10. (Previously Presented) The substrate of claim 1, wherein the metal plate is made of Cu, an Fe-Ni-Cr alloy, an Fe-Cr alloy, an Fe-Ni alloy, Fe or Al.

11. (Previously Presented) The substrate of claim 1, wherein the metal plate has a thickness of 0.05 mm to 0.5 mm.

12. (Previously Presented) A wiring board comprising

the substrate of claim 1, and

a wiring pattern that has been formed on the surface of the insulating film on the substrate.

13-21. (Canceled)